

A

B

C

D








A

B


C

D

Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber
		F.Silks			Legend	GTO
	Surface Material	F.Mask	0.010mm	Solder Resist	Solder Mask	GTS
	Nickel, Gold	Top Surface Finish	0.004mm		Surface Finish	
	Copper	F.Cu	0.035mm		Signal	GTL
	Prepreg		0.110mm	PP-006	Dielectric	
	CF-004	Layer 1	0.035mm		Signal	G1
	Core		0.305mm	Core-031	Dielectric	
	CF-004	Layer 2	0.035mm		Signal	G2
	Prepreg		0.110mm	FR-4	Dielectric	
	CF-004	Layer 3	0.035mm		Signal	G3
	Core		0.305mm	Core-031	Dielectric	
	CF-004	Layer 4	0.035mm		Signal	G4
	Prepreg		0.110mm	PP-006	Dielectric	
	Copper	B.Cu	0.035mm		Signal	GBL
	Nickel, Gold	Bottom Surface Finish	0.004mm		Surface Finish	
	Surface Material	B.Mask	0.010mm	Solder Resist	Solder Mask	GBS
		B.Silks			Legend	GBO

Total thickness: 1.178mm



Eidgenössische Technische Hochschule Zürich
Swiss Federal Institute of Technology Zurich

Project:
Fabrication

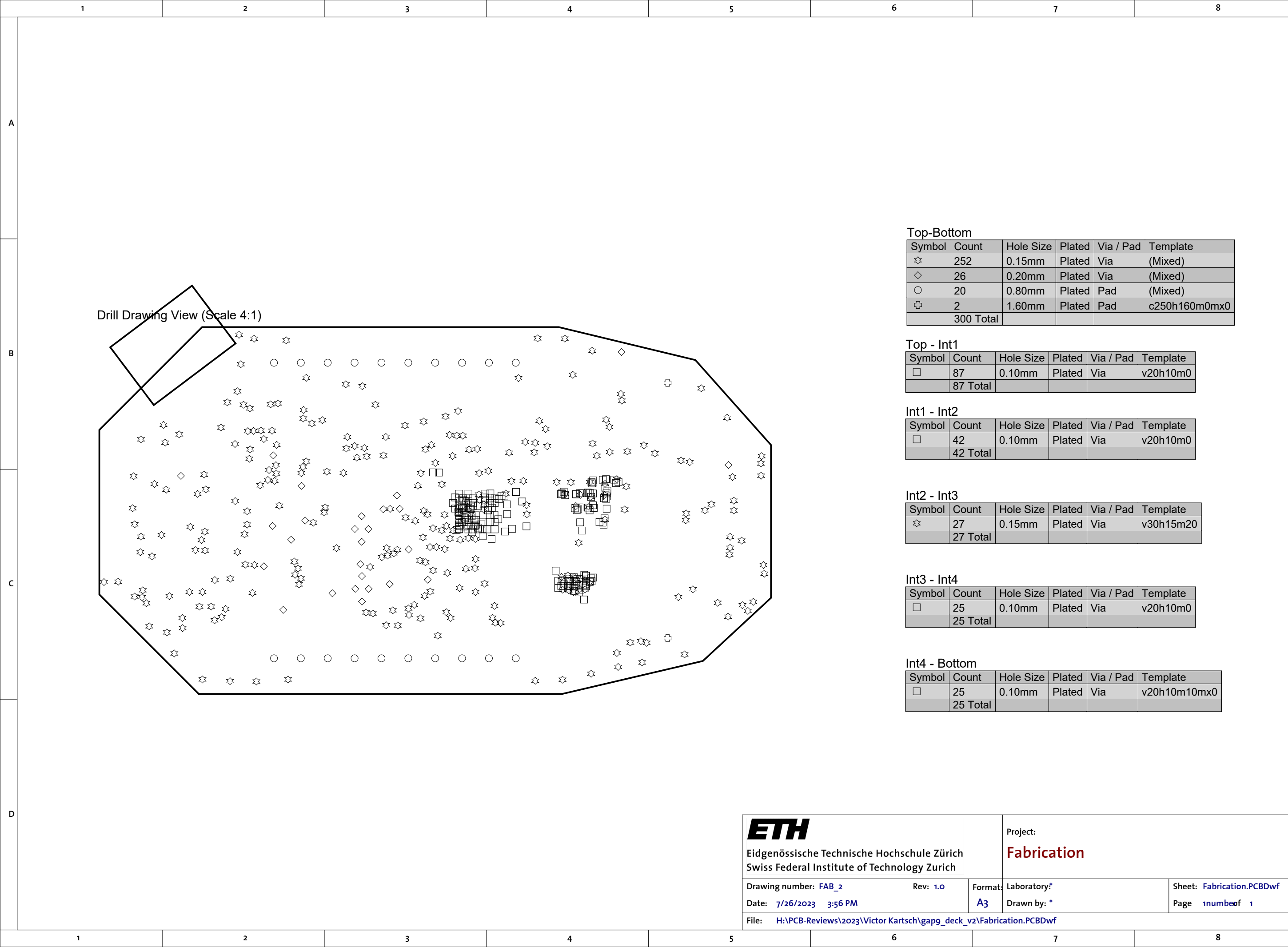
Drawing number: **FAB_2**Rev: 1.0

Format: **A3**

Laboratory: *
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